



12-07-2001

12.301

6715/62028



101909322

To the Honorable Commissioner of Patents and Trademarks

ents or copy thereof.

1. Name of conveying party(ies):

s of receiving party(ies):

Akira Miyagawa
Shuichi Fukuda

Name: Sony Precision Technology, Inc

Internal Address: _____

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of Conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Street Address: 9-17 Nishigotanda 3-chome
Shinagawa-ku, Tokyo, Japan

City _____ State _____ ZIP _____

Execution Date: November 2, 2000

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is _____

A. Patent Application No.(s)

B. Patent No.(s)

09/568,847

405

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

6. Total number of applications and patents involved: 1

Name: Jay H. Maioli
Internal Address: Cooper & Dunham LLP

7. Total fee (37 CFR 3.41): \$ 40.00

Enclosed

Authorized to be charged to deposit account

Street Address: 1185 Avenue of the Americas

8. Deposit account number:

03-3125

(Attach duplicate copy of this page if paying by deposit account)

City: New York State: New York ZIP 10036

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Jay H. Maioli, Reg. No. 27,213
Name of Person Signing

November 26, 2001
Date

Total Number of pages comprising cover sheet: 1

OMB No. 0651-0011 (exp. 4/94)

Do not detach this portion

Mail documents to be recorded with required cover sheet information to:

12/06/2001 DBYRNE 00000036 09568847

Commissioner of Patents and Trademarks
Box Assignments
Washington, D.C. 20231

01 FC:581

40.00 00

Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and to the office of Management and Budget, Paperwork Reduction Project. (0651-0011). Washington, D.C. 20503

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

Method and Apparatus for Measuring Crosstalk of Optical Disc
(title)

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Precision Technology Inc., a Japanese corporation with offices at 9-17, Nishigotanda 3-chome, Shinagawa-ku, Tokyo, Japan (hereinafter reference as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and

said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

International Application Number _____
International Filing Date _____
U.S. Serial Number 09/568,847
U.S. Filing Date May 11, 2000

This assignment executed on the dates indicated below.

Akira Miyagawa Nov. 2, 2000
Name of first or sole inventor Date

Kanagawa, Japan
Residence of first or sole inventor

A. Miyagawa
Signature of first or sole inventor Execution date of U.S. Patent Application

Shuichi Fukuda Nov. 2, 2000
Name of second inventor Date

Tokyo, Japan
Residence of second inventor

Shuichi Fukuda
Signature of second inventor Execution date of U.S. Patent Application

Name of third inventor Date

Residence of third inventor

Signature of third inventor Execution date of U.S. Patent Application